

### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

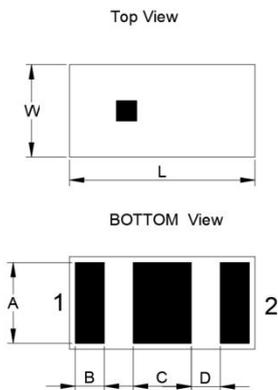
### Specifications

NO.	Parameter		SPC
1	Frequency (MHz)		3700~4300
2	Insertion Loss (dB)@25°C		≤2.5
3	VSWR(In BW)		≤1.8
4	Ripple		≤1.0 dB
5	Attenuation	3000MHz	≥40 dB
		5100MHz	≥40 dB
6	In/Output Impedance (Ω)		50

**Operating & Storage Condition (Component)**  
 Operation Temperature Range: -40°C ~ +85°C  
 Storage Temperature Range: -40°C~ +85°C

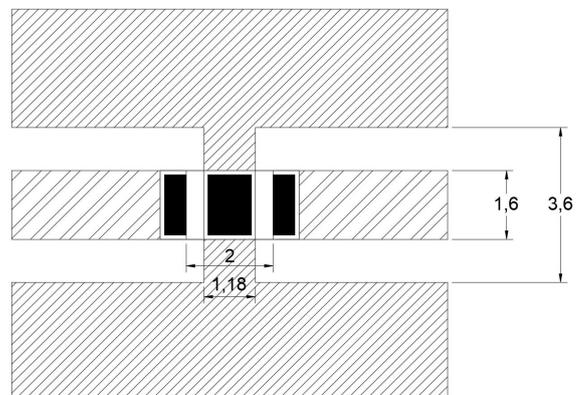
**Storage Condition before Soldering (Included packaging material)**  
 Storage Temperature Range: +5 ~ +40 °C  
 Humidity: 30 to 70% relative humidity

### Construction



PIN	Connection
1	Input Port
2	Output Port

### Mounting Considerations

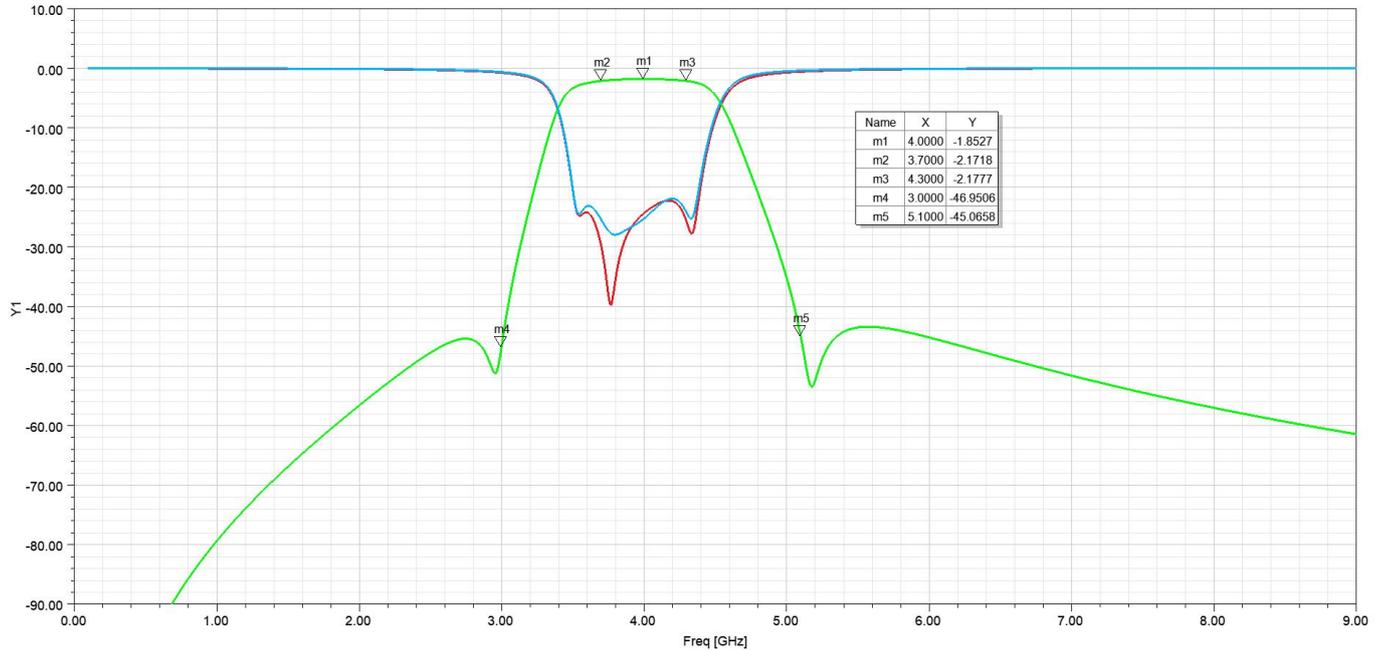


Unit: mm

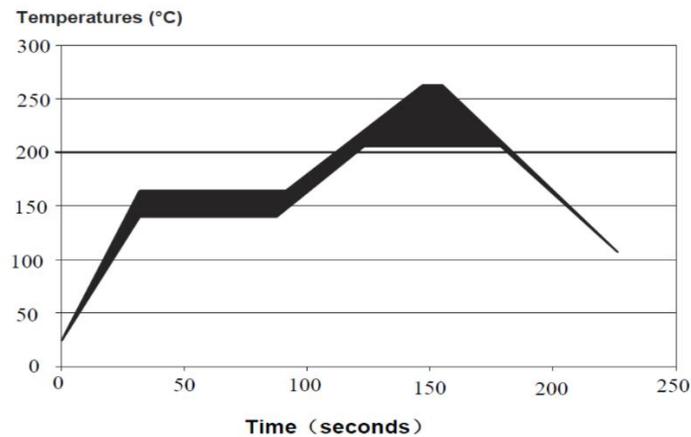
### Dimensions

Figure	Symbol	Dimension (mm)
<p>Top View: Shows a rectangular component with length L and width W.</p> <p>Side View: Shows the thickness T.</p> <p>BOTTOM View: Shows the internal layout with dimensions A, B, C, and D.</p>	L	3.20 ± 0.20
	W	1.60 ± 0.20
	T	0.94 ± 0.20
	A	1.40 ± 0.10
	B	0.50 ± 0.10
	C	1.00 ± 0.10
D	0.50 ± 0.10	

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.